

Powering the AM1806, AM1808, and the AM1810 with the TPS650061

Ben Hopf

Battery Power applications

ABSTRACT

This document details the design considerations of a power solution for the AM1806 and AM1808 (AM1806/08/10) low-power application processor with a TPS650061, three-rail Power Management Unit (PMU) or Power Management IC (PMIC).

Portable application solution size demands a high level of integration and the AM1806/08/10 requires at least three different voltage rails with specific sequencing and reset requirements. The TPS650061 is a highly integrated power solution that can provide the 1.2 V, 1.8 V and 3.3 V rails and RESET signal required by the AM1806/08/10. The TPS650061 has a single step-down converter, two low dropout regulators and a voltage supervisor.

Included in this document is a power solution for the AM1806/08/10. Power requirements, illustrated schematic, operation waveforms, performance data and bill of materials are detailed.

Contents

1	Power Requirements	2
	1.1 Power-On Sequence	3
	1.2 Power-Off Sequence	3
2	Schematic	4
3	Waveforms	4
4	Bill of Materials	6
5	Conclusion	6
6	References	7

List of Figures

1	TPS3805, TPS650061, and AM1806/08/10 Block Diagram.....	2
2	TPS650061 Schematic Diagram.....	4
3	TPS650061 Power-On Ch1-Vin, Ch2-VODC, Ch3-VLDO2, Ch4-VLDO1	5
4	TPS650061 Power-On and /Reset Ch1-/RST, Ch2-VODC, Ch3-VLDO2, Ch4-VLDO1	5
5	TPS650061 Power-Off Ch1-/RST, Ch2-VODC, Ch3-VLDO2, Ch4-VLDO1	6

List of Tables

1	AM1806/08/10 Power Requirements	2
2	Bill of Materials	6

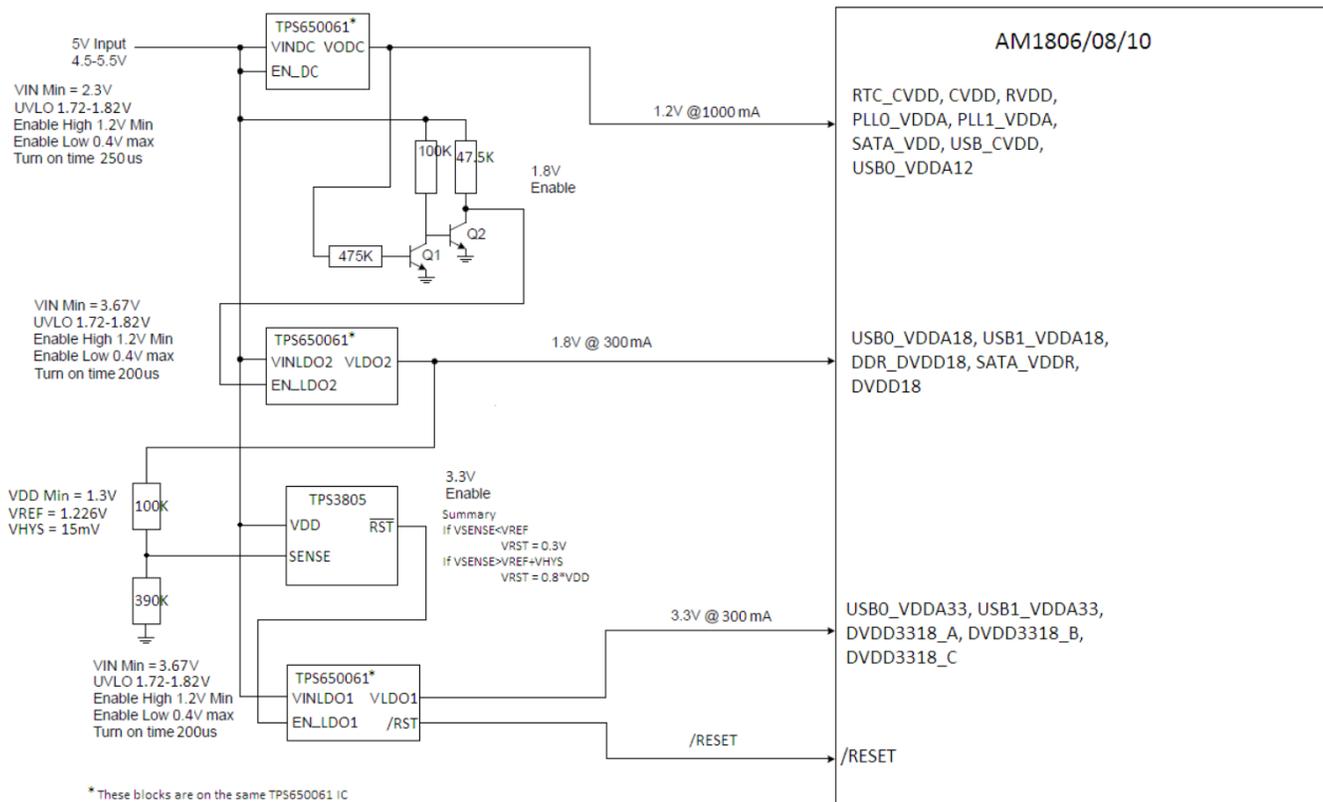


Figure 1. TPS3805, TPS650061, and AM1806/08/10 Block Diagram

1 Power Requirements

The AM1806/08/10 power requirements are listed in [Table 1](#).

Table 1. AM1806/08/10 Power Requirements

RAIL NAME	VOLTAGE (V)	I _{max} (mA)	TOLERANCE
RTC_CVDD	1.2	1	-25%, +10%
CVDD	1.2	375	-9.75%, +10%
RVDD, PLL0_VDDA, PLL1_VDDA, SATA_VDD, USB_CVDD, USB0_VDDA12	1.2	200	-5%, +10%
USB0_VDDA18, USB1_VDDA18, DDR_DVDD18, SATA_VDDR, DVDD18	1.8	180	±5%
USB0_VDDA33, USB1_VDDA33	3.3	24	±5%
DVDD3318_A, DVDD3318_B, DVDD3318_C	1.8/3.3	50/90	±5%

The TPS650061 meets these power requirements with its single step-down converter, two low dropout regulators and voltage supervisor.

1.1 Power-On Sequence

To meet the AM1806/08/10 power-on requirements, the 1.2V rail must power on first, then the 1.8V rail, and lastly, the 3.3 V rail. After all 3 rails are up, the RESET may be released. To ensure this power up sequence, the 1.2V enable is connected to VIN and the output is connected to EN_LDO2 through two transistors. The output of LDO2, VLDO2, is connected to the sense input of an SVS that has its RESET output connected to EN_LDO1. To ensure that the TPS650061 doesn't assert its reset until all three supplies are up, RST is pulled up to VLDO2, MR is pulled up to VODC, and RSTSNS is connected to VLDO1 with a resistor divider. The proper connections for this power-on sequencing are shown in [Figure 2](#).

Notice the following considerations in selecting components for the circuit:

- The resistor divider on RSTSNS is such that if VLDO1 goes below 3.3 V – 5% (3.125 V), reset becomes active (opens).
 - Because \overline{RST} is pulled-up to VLDO2 and /MR is pulled up to VODC, it will only go high if VODC, VLDO1, and VLDO2 are all present.
- The RSTSNS pin may be connected to an external RC network to set the deglitch timing for triggering a reset when the RSTSNS pull-up voltage falls below the set threshold.

Per the excerpt from the AM1806/08/10 datasheet, the device should be powered-on in the following order:

1. RTC (RTC_CVDD) may be powered from an external device (such as a battery) prior to all other supplies being applied or powered-up at the same time as CVDD. If the RTC is not used, RTC_CVD should be connected to CVDD. RTC_CVDD should not be left unpowered while CVDD is powered.
2. Core logic supplies:
 - (a) CVDD core logic supply
 - (b) Other 1.2V logic supplies (RVDD, PLL0_VDDA, PLL1_VDDA, USB_CVDD). If voltage scaling is not used on the device, groups 2a) and 2b) can be controlled from the same power supply and powered up together.
3. All 1.8V IO supplies (DVDD18, DDR_DVDD18, USB0_VDDA18) and any of the LVCMOS IO supply groups used at 1.8V nominal (DVDD3318_A, DVDDA3318_B, or DVDD3318_C).
4. All analog 3.3V PHY supplies (USB0_VDDA33; this is not required if USB0 is not used) and any of the LVCMOS IO supply groups used at 3.3V nominal (DVDDA3318_A, DVDDA3318_B, or DVDDA3318_C).

There is no specific required voltage ramp rate for any of the supplies as long as the LVCMOS supplies operated at 3.3V (DVDDA3318_A, DVDDA3318_B, or DVDDA3318_C) never exceed STATIC 1.8V supplies by more than 2 volts. RESET must be maintained active until all power supplies have reached their nominal values.

It is mentioned in the AM1806 Silicon Errata that the DVDD18 voltage rail can pull up to 2.7 V when using dual-voltage IOs at 3.3 V. To address this potential issue, workaround (1a) from the errata is implemented. This workaround asserts that maintaining sufficient bulk capacitance on the DVDD18 supply will ensure that it is not pulled up to 2.7 V. The capacitor value selected was calculated using the equation $I = C \times (dV/dt)$, where dV/dt is the ramp rate of the DVDD3318_x supply (around 280 μ s) and I is the maximum leakage current into the DVDD18 supply (140 mA). The calculation gives a capacitance value of 11.88 μ F, so the nearest valued available capacitor (22 μ F) was chosen and connected to the 1.8 V output rail.

1.2 Power-Off Sequence

For the AM1806/08/10, the power supplies can be powered off in any order as long as the LVCMOS supplies operated at 3.3V (DVDDA3318_A, DVDDA3318_B, or DVDDA3318_C) never exceed STATIC 1.8V supplies by more than 2 volts. There is no specific required voltage ramp down rate for any of the supplies (except as required to meet the above mentioned voltage condition).

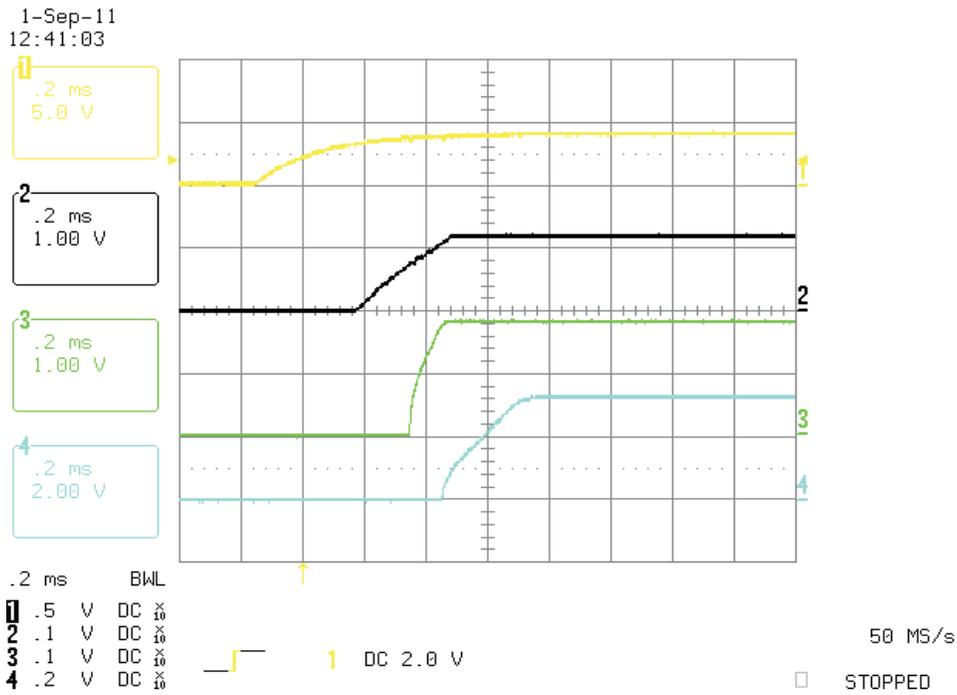


Figure 3. TPS650061 Power-On Ch1-Vin, Ch2-VODC, Ch3-VLDO2, Ch4-VLDO1

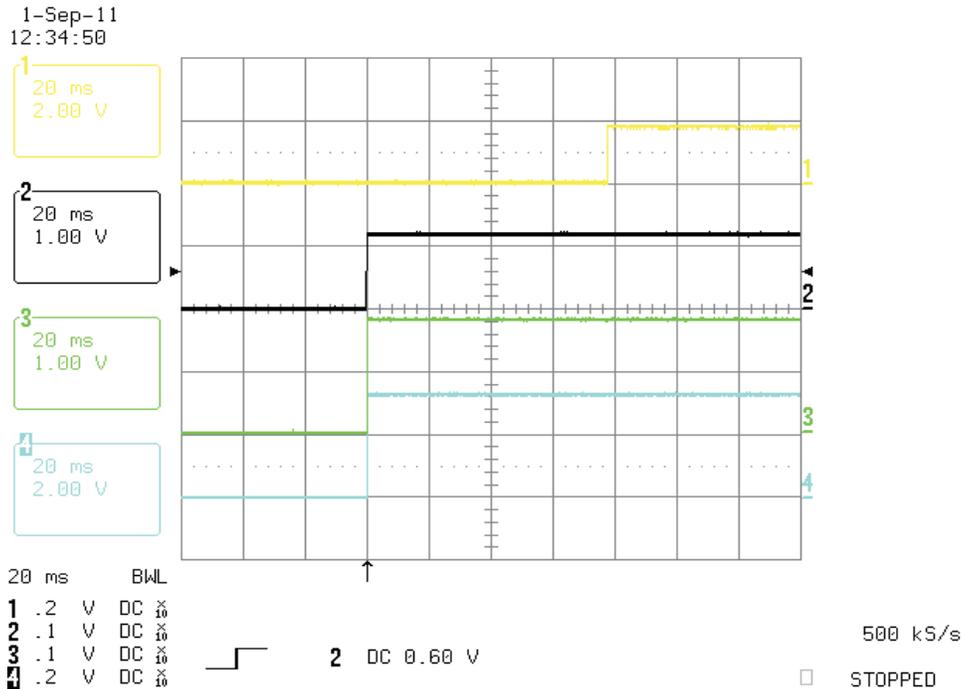


Figure 4. TPS650061 Power-On and /Reset Ch1-/RST, Ch2-VODC, Ch3-VLDO2, Ch4-VLDO1

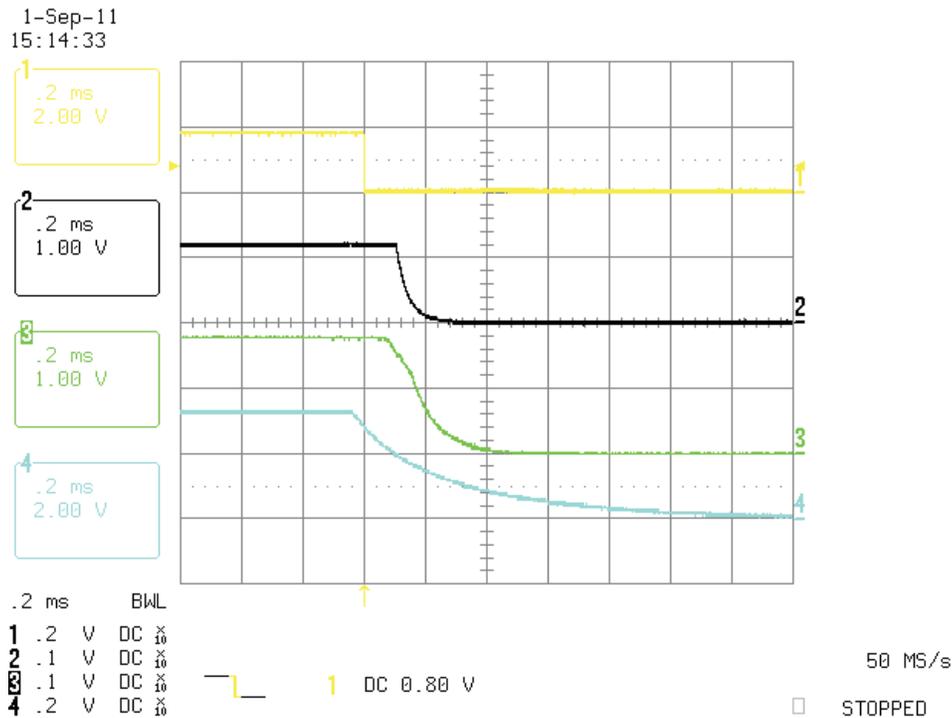


Figure 5. TPS650061 Power-Off Ch1–/RST, Ch2–VODC, Ch3–VLDO2, Ch4–VLDO1

4 Bill of Materials

The bill of materials is displayed in [Table 2](#).

Table 2. Bill of Materials

Count	RefDes	Value	Description	Size	Part Number	MFR
3	C1, C6, C8	10 μ F	Capacitor, Ceramic, 10 V, X5R, 10%	0805	Std	Std
1	C9	22 μ F	Capacitor, Ceramic, 10 V, X5R, 10%	0805	Std	Std
2	C2, C3	2.2 μ F	Capacitor, Ceramic, 10 V, X5R, 10%	0603	Std	Std
2	C4, C5	0.1 μ F	Capacitor, Ceramic, 16 V, X7R, 10%	0603	Std	Std
1	C7	22 pF	Capacitor, Ceramic, 50 V, COG, 5%	0603	Std	Std
1	L1	2.2 μ F	Inductor, SMT, 2.0 A, 110 milliohm	0.118 x 0.118 inch	LPS3015-222ML	Coilcraft
3	R1, R2, R9	4.5 k Ω	Resistor, Chip, 1.16 W, 1%	0603	Std	Std
4	R3, R5 R6, R11	475 k Ω	Resistor, Chip, 1.16 W, 1%	0603	Std	Std
2	R7, R10	100 k Ω	Resistor, Chip, 1.16 W, 1%	0603	Std	Std
1	R4	255 k Ω	Resistor, Chip, 1.16 W, 1%	0603	Std	Std
1	R8	390 k Ω	Resistor, Chip, 1.16 W, 1%	0603	Std	Std
1	U1	TPS650061RUK	IC, 2.25 MHz Step Down Converter with Dual LDOs and SVS	QFN	TPS650061RUK	TI
1	U2	TPS3805	IC, Voltage Detector	SOP-5 (DCK)	TPS3805	TI
2	Q1, Q2	MMBT2222A	Transistor, NPN, High-Performance, 500 mA	SOT-23	MMBT2222A	Fairchild

5 Conclusion

The TPS650061 provides a low cost, comprehensive power solution for the AM1806/08/10. A 1.2 V rail (capable of supplying 1 A) is powered on followed by a 1.8 V rail (300 mA) then a 3.3 V rail (300 mA); once all three supplies have reached minimum regulation, RESET goes high (i.e., rises to its pull-up voltage). This meets the power requirements of the AM1806/08/10.

6 References

1. TPS650061 Datasheet ([SLVS810B](#))
2. AM1806 Datasheet ([SPRS658C](#))
3. AM1808 Datasheet ([SPRS653B](#))
4. AM1810 Datasheet ([SPRS709A](#))
5. Powering Freon with TPS65070 Application Report ([SLVA371A](#))
6. DM355 Reference Design ([SLVR331B](#))
7. AM1806 Silicon Errata ([SPRZ314B](#))

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated